

## Replisaurus to Collaborate with IMEC on 3D Integration Research

*A Joint Development Program Will Employ S.E.T.'s High Accuracy FC300 System to Explore Advanced 3D Applications*

**Saint Jeoire, France, Jan. 13, 2009** – S.E.T. Smart Equipment Technology, a wholly-owned subsidiary of Replisaurus Technologies and a leading supplier of high accuracy die-to-die (D2D), die-to-wafer (D2W) bonding and nanoimprint lithography solutions, announced today that they will collaborate with IMEC, one of Europe's leading independent nanoelectronics research institutes, on the development of die pick-and-place and bonding processes for 3D chip integration, using S.E.T.'s Flip Chip bonder equipment.

IMEC's 3D integration program explores 3D technology and design for applications in various domains, focusing on 3D wafer-level packaging and 3D stacked-ICs to find innovative solutions for the cost-effective use of 3D interconnects.

The joint development program will employ S.E.T.'s FC300, which is a high-accuracy ( $\leq 0.5 \mu\text{m}$ ), high force (4,000N) device bonder system for die-to-die and die-to-wafer bonding on wafers up to 300 mm. The program is scheduled to begin during the first quarter of 2009, at which time S.E.T. will enter the IMEC's Industrial Affiliation Program (IIAP) on 3D integration. The parties will collaborate to develop highly-accurate pick-and-place processes and low-temperature bonding processes, which are required by advanced 3D integration schemes.

"The integration of the FC300 will be a welcome addition to our 3D program, as is the participation of S.E.T. and Replisaurus," said Luc van den Hove, Executive Vice President and COO of IMEC. "The Replisaurus and S.E.T. technologies are very interesting for advanced packaging applications, and the integration of this tool in particular will help complete our program."

"IMEC's installation of the FC300 is fully in line with Replisaurus' product and technology portfolio, which offers game-changing opportunities to the global chip market," said James Quinn, CEO of Replisaurus. "IMEC's advanced 3D integration program is recognized worldwide, and the FC300 is extremely complimentary to Replisaurus' ElectroChemical Pattern Replication (ECPR) technology, which is well-suited for advanced 3D integration and related applications."

### **About Replisaurus Technologies**

Replisaurus Technologies, Inc. has developed a revolutionary metallization technology targeted at key growth markets such as integrated passives, copper pillars and 3D integration (TSV). The ElectroChemical Pattern Replication (ECPR™) process offers a simple and cost effective integrated solution eliminating several traditional process steps thereby reducing complexity. ECPR is a fab-friendly, environmentally clean process which does not use any solvents, developers or strippers and has extremely fast plating rates. The ECPR technology is a "Design Enabling" technology for integrated passives enabling advanced designs, eliminating the need for prototyping and dummy plating patterns. The electrochemical replication principle of ECPR combines the precision and resolution of advanced lithography with the ease and efficiency of electrochemical deposition into one single integrated process solution.

For more information please visit us at [www.replisaurus.com](http://www.replisaurus.com).

**About S.E.T.**

S.E.T., Smart Equipment Technology is a world leading supplier of High Accuracy Die-to-Die, Die-to-Wafer Bonding and Nanoimprint Lithography solutions. With more than 250 Device Bonders installed worldwide, S.E.T. is globally renowned for the unsurpassed placement accuracy and the high flexibility of its Flip Chip bonders. From the KADETT semi-automated R&D Device Bonder, through the automated FC150 and FC300 to the production FC250, S.E.T. offers a continuous process path from research to production. S.E.T. bonders cover most bonding technologies and offer the unique ability to handle and bond both fragile and small components onto substrates up to 300 mm. Further information on the FC300 is available on [www.set-sas.fr](http://www.set-sas.fr).

**About IMEC**

IMEC is a world-leading independent research center in nanoelectronics and nanotechnology. IMEC vzw is headquartered in Leuven, Belgium, has a sister company in the Netherlands, IMEC-NL, offices in the US, China and Taiwan, and representatives in Japan. Its staff of more than 1600 people includes more than 500 industrial residents and guest researchers. In 2007, its revenue (P&L) was EUR 244.5 million. IMEC's More Moore research aims at semiconductor scaling towards sub-32nm nodes. With its More than Moore research, IMEC looks into technologies for nomadic embedded systems, wireless autonomous transducer solutions, biomedical electronics, photovoltaics, organic electronics and GaN power electronics. IMEC's research bridges the gap between fundamental research at universities and technology development in industry. Its unique balance of processing and system know-how, intellectual property portfolio, state-of-the-art infrastructure and its strong network worldwide position IMEC as a key partner for shaping technologies for future systems. Further information on IMEC can be found on [www.imec.be](http://www.imec.be).

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